

# SOT1461-2

WLCSP13, wafer level chip-scale package; 13 bumps; 1.19 mm x 1.99 mm x 0.5 mm body

18 May 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP13
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Package body material type</b>	X (other)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-2-2017
<b>Manufacturer package code</b>	SOT1461

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.96	-	1.99	2.02	mm
E	package width	1.16	-	1.19	1.22	mm
A	seated height	0.46	-	0.5	0.54	mm
A <sub>2</sub>	package height	-	-	-	-	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	13	-	



2. Package outline

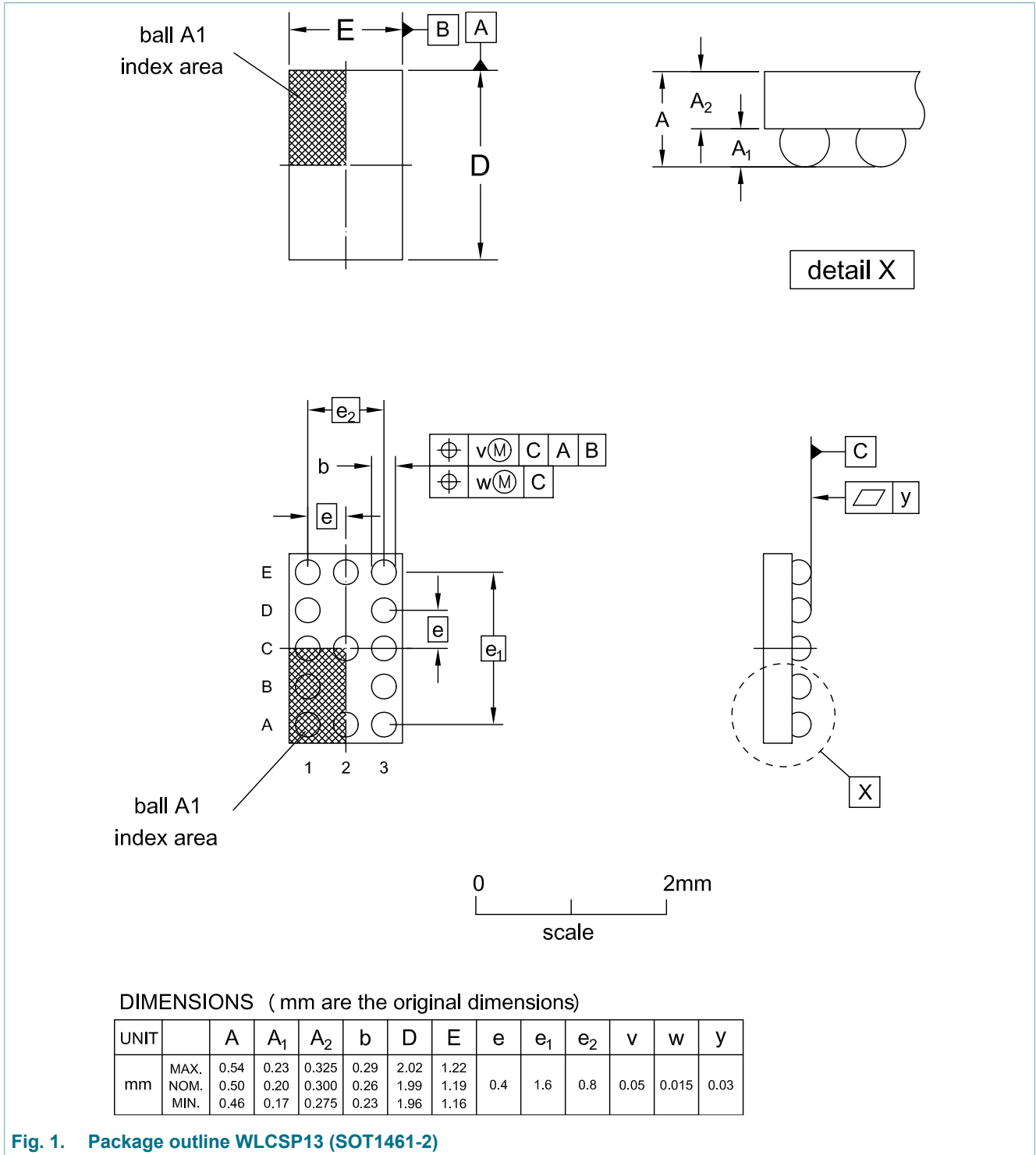


Fig. 1. Package outline WLCSP13 (SOT1461-2)

### 3. Legal information

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